Lenovo to Showcase How Smarter Revolutionizes HPC at SC23

Article (withdrawn product)

SC23 is November 13-16, 2023

Supercomputing 23, the international conference for high performance computing, networking, storage, and analysis, is being held next week, November 13-16, at the Colorado Convention Center in Denver, Colorado.

Lenovo is gearing up for a full throttled, engaging experience including booth theater sessions, customer briefings, and interactive demos and we encourage you to visit us in **Booth 601**. Lenovo would like to thank our partners at SC23: AMD, Intel and NVIDIA for their valued support at the show, and ongoing partnership in the HPC community.

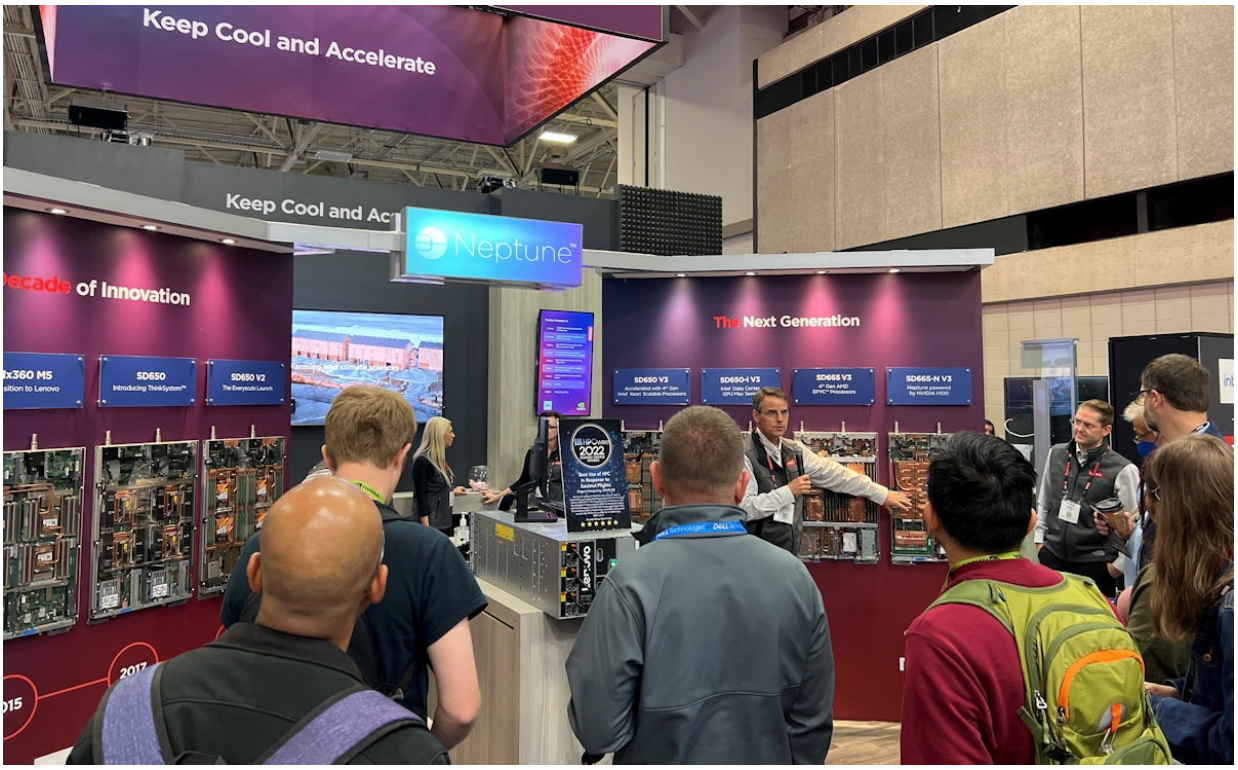

Figure 1. Pat Moakley presenting to attendees at SC22

New and refreshed offerings

There will be a lot to see and experience, but here is a glimpse into what participants will learn about and find from Lenovo at SC23:

NEW: TruScale Hybrid Cloud for HPC-as-a-Service

Lenovo is leading the industry with this new solution that enables customers to utilize all on-premise resources with the ability to leverage the cloud in a simple, secure and scalable way.

NEW: TruScale for Artificial Intelligence & Machine Learning

Lenovo in partnership with UbiOps and WEKA developed a solution to provide HPC and AI teams with a powerful, production-ready solution for deployment, training, and management of machine learning and deep learning models and workflows. This new solution can:

- Train, deploy, and manage all your data science and machine learning models in a turn-key production environment with a scalable compute infrastructure.
- Scale your AI workloads dynamically with usage and grow easily with autoscaling capability.
- Leverage state-of-the-art high-performance GPU for accelerating deep learning.

REFRESHED: Lenovo Intelligent Computing Orchestration (LiCO)

LiCO is a software solution that simplifies the use of clustered computing resources for AI model development and training, and HPC workloads. Part of Lenovo EveryScale HPC & AI Software Stack, the unified platform simplifies interaction with the underlying compute resources, enabling users to take advantage of popular open-source cluster tools while reducing the effort and complexity of using it for HPC and AI. LiCO can integrate with a variety of HPC and AI hardware and software solutions, making it adaptable to existing infrastructures and workflows.

Its value lies in simplifying workload management, optimizing resource usage, and enhancing collaboration, ultimately leading to increased productivity, reduced operational costs, and improved scalability in both on-premises and hybrid cloud environments.

The newest version, LiCO 7.2, extends the HPC and AI capabilities to increase LiCO agnosticism and flexibility. In addition to supporting the latest hardware and workstations from our portfolio, we will also permit non-Lenovo hardware in the cluster.

REFRESHED: Lenovo Distributed Storage Solution for IBM Spectrum Scale (DSS-G)

A software-defined storage (SDS) solution for dense scalable file and object storage suitable for high-performance and data-intensive environments. DSS-G combines the performance of Lenovo ThinkSystem servers, Lenovo storage enclosures, and industry leading IBM Spectrum Scale software, to offer a high performance, scalable building block approach to modern storage needs.

Lenovo DSS-G is fulfilled through Lenovo Scalable Infrastructure (LeSI), which offers a flexible framework for the development, configuration, build, delivery and support of engineered and integrated data center solutions.

New featured releases:

- ThinkSystem SR655 V3 server - Based on the powerful AMD EPYC processor
- ThinkSystem D4390 Direct Attached Storage - Extra capacity JBOD supporting 22TB drives
- NVIDIA ConnectX-7 networking cards – Fastest data throughput
- Broadcom 450w-16e Gen 4 SAS adapter - 24Gb SAS connectivity

Engaging booth theater sessions

What do generative AI, digital twins, storage, liquid cooling, and sustainability all have in common? Each will have session in Lenovo’s booth theater! You’ll hear from some of the industry’s respected thought leaders from Lenovo and our partners where they’ll share their insight and expertise on these topics and more. Check the schedule at the booth each day.

Interactive demos

Our interactive booth demos will feature:

- Neptune liquid cooling
- Asset Recovery Services
- HPC professional services
- Enterprise generative AI
- Digital twins
- Legion products for STEM

Small group multi-customer briefings

Subject matter experts are hosting five multi-customer sessions:

- Monday, November 13
  - **2:00-3:00pm**: How genomics solutions can enable researchers to meet the increase in data to speed up time to scientific insight.
- Tuesday, November 14
  - **10:00-11:00am**: How generative AI hardware and software can deploy on-premise Large Language Models that can be customized for your company.
  - **2:00-3:00pm**: How fully managed on-prem HPC-as-a-Service solutions can scale with your needs to ensure you only pay for you use.
- Wednesday, November 15
  - **10:00-11:00am**: How DreamWorks Animation uses compute-intensive CG animation production processes that push the boundaries of digital animation and brings blockbuster movies to the big screen.
  - **2:00-3:00pm**: Infrastructure and software can help predict and deliver early and precise warnings of severe weather.

Space is limited for these sessions, so please stop by booth 601 to register.

More information

With Lenovo, there will be a lot for you to see and experience. We look forward to seeing you in Denver for SC23! For more information on Lenovo's HPC solutions, visit https://www.lenovo.com/HPC.

About the author

Patrick Moakley is the Director of Marketing for HPC & AI at Lenovo Infrastructure Solutions Group. He has over 30 years in IT sales and marketing of x86 systems at Lenovo and IBM and has a Bachelor's degree in Economics from the University of Wisconsin-Madison.

Related product families

Product families related to this document are the following:

- Artificial Intelligence
- High Performance Computing

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